

Chip Resistor Networks

Type: **EXBD:1206**
EXBE:1608
EXBA:2512
EXBQ:1506

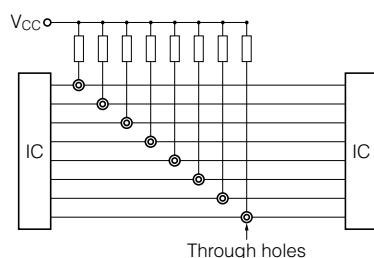


■ Features

- High density placing for digital signal circuits
 - Bussed 8 or 15 resistors for pull up/down circuits
 EXBD: 3.2 mm × 1.6 mm × 0.55 mm, 0.635 mm pitch
 EXBE: 4.0 mm × 2.1 mm × 0.55 mm, 0.8 mm pitch
 EXBA: 6.4 mm × 3.1 mm × 0.55 mm, 1.27 mm pitch
 EXBQ: 3.8 mm × 1.6 mm × 0.45 mm, 0.5 mm pitch
 - Available direct placing on the bus line by means of half pitch spacing without through-holes on PWB
 ("High density placing" is shown below)
- High speed mounting using conventional placing machine
- Reference Standard: IEC 60115-9, JIS C 5201-9, EIAJ RC-2130
- RoHS compliant

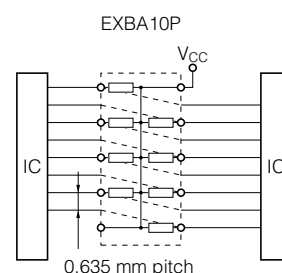
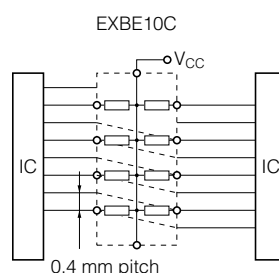
<High density placing>

Pull up resistors



No through hole

Direct placement on the bus line



■ Packaging Methods, Land Pattern, Soldering Conditions and Safety Precautions

Please see Data Files

■ Explanation of Part Numbers

